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To the Assistant Commissioner for F

1. Name of conveying party(ies):

John Lee Colbert
John Saunders Corbin, Jr.
Roger Duane Hamilton
Danny E. Massey
Arvind Kumar Sinha

Additional names of conveying party(ies) attached?

☐ yes ☒ no

3. Nature of Conveyance

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: 07/23/01, 07/26/01

2. Name and address of receiving party(ies):

Name: International Business Machines Corporation

Internal Address:

Street Address: New Orchard Road

City Armonk

State New York Zip 10504

Additional name(s) & address(es) attached? ☐ yes ☒ no

4. Application number(s) or patent number(s):

TITLE: Heat Pipe Heat Sink Assembly for Cooling Semiconductor Chips

If this document is being filed together with a new application, the execution date of the application is July 27, 2001

A. Patent Application No(s).

B. Patent No(s).

Docket No. ROC920010027US1

Serial No.

Additional numbers attached? ☐ Yes ☒ No

Name and address of party to whom correspondence concerning document should be mailed:

Robert R. Williams
IBM Corporation - Dept. 917
3605 Highway 52 North
Rochester, MN 55901-7829

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

☐ Enclosed

☒ Authorized to be charged to deposit account
☒ Total fee due
☒ Any deficiencies in the enclosed fees

8. Deposit account number:

09-0465

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Robert R. Williams, Reg. #P-48,395
Name of Person Signing

Robert R. Williams
Signature

July 27, 2001

Date

Total number of pages comprising cover sheet: 1

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ASSIGNMENT

Whereas, we

- | | | |
|-----|---|---|
| (1) | John Lee Colbert
County of Olmsted | City of Byron,
and State of Minnesota, |
| (2) | John Saunders Corbin, Jr.
County of Travis | City of Austin,
and State of Texas, |
| (3) | Roger Duane Hamilton
County of Olmsted | City of Eyota,
and State of Minnesota, |
| (4) | Danny E. Massey
County of Travis | City of Austin,
and State of Texas, |
| (5) | Arvind Kumar Sinha
County of Olmsted | City of Rochester,
and State of Minnesota, |

have invented certain improvements in

HEAT PIPE HEAT SINK ASSEMBLY FOR COOLING SEMICONDUCTOR CHIPS

and have executed, respectively, a United States patent application therefor on

Dates Inventors

Signed			
Declaration	(1) July 23,	, 2001	(2) <i>July 26</i> , 2001
	(3) July 23,	, 2001	(4) <i>July 26</i> , 2001
	(5) July 23,	, 2001.	

And whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we the above named hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed

Inventor (1)	at <u>Rochester, Minnesota</u>	<u>John L. Colbert</u> (John L. Colbert) First Name Initial Last Name	Inventor Signature
	on <u>July 23</u> , 2001.		
Inventor (2)	at <u>Austin, Texas</u>	<u>John S. Corbin, Jr.</u> (John S. Corbin, Jr.) First Name Initial Last Name	Inventor Signature
	on <u>26 July</u> , 2001.		
Inventor (3)	at <u>Rochester, Minnesota</u>	<u>Roger D. Hamilton</u> (Roger D. Hamilton) First Name Initial Last Name	Inventor Signature
	on <u>July 23</u> , 2001.		
Inventor (4)	at <u>Austin, Texas</u>	<u>Danny E. Massey</u> (Danny E. Massey) First Name Initial Last Name	Inventor Signature
	on <u>July 26</u> , 2001.		
Inventor (5)	at <u>Rochester, Minnesota</u>	<u>Arvind K. Sinha</u> (Arvind K. Sinha) First Name Initial Last Name	Inventor Signature
	on <u>July 23</u> , 2001.		